


INTERNATIONAL DIRECTORY OF WAFER SCRIBING & DICING SYSTEMS

Advertisers are listed in Boldface type. Refer to our Editorial Calendar for upcoming Directories.

COMPANY HEADQUARTERS	WAFER SCRIBING SYSTEMS	SAW DICING SYSTEMS	LASER DICING SYSTEMS
Company Street Address City, State, Country Telephone Website Note: CM = Contact Manufacturer	Method L - Laser, M - Mechanical P - Plasma, S - Saw Automation LU - Loading & Unloading WA - Wafer Alignment CD - Cleaning & Drying Specifications (Max.) WD - Wafer Diameter FR - Feed Rate / Speed Models (Qty)	Method L - Laser, M - Mechanical P - Plasma, S - Saw Automation LU - Loading & Unloading WA - Wafer Alignment CD - Cleaning & Drying Specifications (Max.) WD - Wafer Diameter FR - Feed Rate / Speed Models (Qty)	Method L - Laser, M - Mechanical P - Plasma, S - Saw Automation LU - Loading & Unloading WA - Wafer Alignment CD - Cleaning & Drying Specifications (Max.) WD - Wafer Diameter FR - Feed Rate / Speed Models (Qty)
Advanced Dicing Technologies LTD. Hi-Tech Park South P.O. Box 87 Yokneam, 20692 Israel Tel: +972-4-854-5222 www.adt-co.com		Method: Saw Automation: LU, WA, CD WD: 300 mm FR: 700 mm/s Models (3)	
Advanced Laser Separation International N.V. Platinawerf 20-G 6641 TL Beuningen (Gld), The Netherlands Tel: +31-24-678-2888 www.alsi-international.com			Method: Laser Automation: LU, WA, CD WD: 300 mm FR: 500 mm/s Models (3)
Aremco Products, Inc. P.O. Box 517, 707-B Executive Blvd. Valley Cottage, NY 10989 Tel: +1-845-268-0039 www.aremco.com		Method: Saw Automation: WA WD: 150 mm FR: CM Models (2)	
Disco Corporation 13-11 Omori-kita, 2-chome, Ota-ku Tokyo 143-8580, Japan Tel: +81-3-4590-1100 www.disco.co.jp	Method: Laser Automation: LU, WA WD: 300 mm FR: 1,000 mm/s Models (2)	Method: Saw Automation: LU, WA, CD WD: 300 mm FR: 1,000 mm/s Models (14)	Method: Laser Automation: LU, WA, CD WD: 300 mm FR: 1,000 mm/s Models (1)
Dynatex International 5577 Skylane Blvd. Santa Rosa, CA 95403 Tel: +1-707-542-4227 www.dynatex.com	Method: Mechanical Automation: CM WD: 200 mm FR: 100 mm/s Models (1)		
Electro Scientific Industries, Inc. (ESI) 13900 NW Science Park Drive Portland, OR 97229 Tel: +1-503-641-4141 www.esi.com	Method: Laser Automation: LU, WA, CM WD: 100 mm FR: CM Models (4)		Method: Laser Automation: CM WD: CM FR: CM Models (1)
EO Technics Co., Ltd. 864-4 Kwanyang 2 Dong Dongan-ku, Anyang, Korea Tel: +82-31-422-2501 www.eotechnics.com			Method: Laser Automation: CM WD: CM FR: CM Models (1)
Fonon Display & Semiconductor Systems 400 Rinehart Road, Suite 1000 Lake Mary, FL 32746 Tel: +1-407-829-2613 www.fonondss.com			Method: Laser Automation: WA, CM WD: 300 mm FR: 500 mm/s Models (1)

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Hanmi Semiconductor Co., Ltd. 532-2 Gajwa-Dong, Seo-Gu Incheon, South Korea Tel: +82-32-571-9100 www.hanmisemi.com 			Method: Laser Automation: CM WD: 300 mm FR: CM Models (1)
Jenoptik AG Carl-Zeiss-Strasse 1 07739 Jena, Germany Tel: +49-3641-65-1000 www.jenoptik.us			Method: Laser Automation: LU, WA, CM WD: 300 mm FR: 1,000 mm/s Models (1)
Joyo Engineering Co., Ltd. 1-5-12 Edanishi, Aoba-ku, Yokohama-shi Kanagawa 225-0014, Japan Tel: +81-45-912-4411 www.joyo-eng.co.jp	Method: Mechanical Automation: WA, CM WD: 150 mm FR: CM Models (2)		
J. P. Sercel Associates 220 Hackett Hill Road Manchester, NH 03102 Tel: +1-603-518-3200 www.jpsalaser.com	Method: Laser Automation: WA, CM WD: CM FR: CM Models (1)		Method: Laser Automation: LU, WA, CM WD: 300 mm FR: CM Models (2)
Loadpoint Ltd. Chelworth Industrial Estate, Cricklade Swindon, Wilts. SN6 6HE, England Tel: +44-1793-751160 www.loadpoint.co.uk		Method: Saw Automation: WA, CM WD: 300 mm FR: 500 mm/s Models (3)	
Loomis Industries, Inc. 1204 Church Street St. Helena, CA 94574 Tel: +1-707-963-4111 www.loomisinc.com	Method: Mechanical Automation: WA WD: 150 mm FR: CM Models (1)		
Micro Processing Technology, Inc. (MPT) 936 Dewing Avenue, Suite B Lafayette, CA 94549 Tel: +1-925-299-8940 www.microptech.com	Method: Mechanical Automation: CM WD: 200 mm FR: 1,000 mm/s Models (1)		
NPOS Technologies Inc. 1922 Santa Rosa Avenue Pasadena, CA 91104 Tel: +1-626-398-0327 www.npos-usa.com	Method: Mechanical Automation: CM WD: 200 mm FR: 100 mm/s Models (3)		

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Opto System Co., Ltd. 100 Nogami, Miyamaki, Kyotanabe City Kyoto 610-0313, Japan Tel: +81-774-68-4440 www.opto-system.co.jp	Method: Laser, Mechanical Automation: LU, WA WD: 100 mm FR: 50 mm/s Models (1 each)		
Panasonic Factory Solutions Co., Ltd. 2-7, Matsubo-cho, Kadoma Osaka 571-8502, Japan Tel: +81-6-6905-5535 www.industrial.panasonic.com			Method: Plasma Automation: CM WD: 300 mm FR: CM Models (1)
Panasonic Welding Systems Co., Ltd. 3-1-1, Inazu-cho, Toyonaka-city Osaka 561-0854, Japan Tel: +81-6-6862-1121 www.industrial.panasonic.com	Method: Laser Automation: CM WD: CM FR: CM Models (1)		
Planar Corporation 2 Partizansky Ave. Minsk 220033, Republic of Belarus Tel: +375-17-223-7211 www.planar.by	Method: Laser Automation: CM WD: 150 mm FR: 600 mm/s Models (3)	Method: Saw Automation: LU, WA, CD WD: 300 mm FR: 600 mm/s Models (3)	
Shibuya Kogyo Co., Ltd. Ko-58 Mameda-Honmachi, Kanazawa Ishikawa 920-8681, Japan Tel: +81-76-262-1200 www.shibuya.co.jp			Method: Laser/Water Automation: CM WD: CM FR: CM Models (1)
Synova SA Chemin de la Dent d'Oche CH-1024 Ecublens, Switzerland Tel: +41-21-694-3500 www.synova.ch		Method: Saw + Laser/Water Automation: LU, WA, CD WD: 300 mm FR: 600 mm/s Models (1)	Method: Laser/Water Automation: LU, WA, CD WD: 300 mm FR: 1,000 mm/s Models (4)
Thermocarbon Inc. 391 Melody Lane Casselberry, FL 32707 Tel: +1-407-834-7800 www.dicing.com		Method: Saw Automation: CM WD: CM FR: CM Models (1)	
Tokyo Seimitsu Co., Ltd. 2968-2 Ishikawa-machi, Hachioji-shi Tokyo 192-8515, Japan Tel: +81-42-642-1701 www.accretech.jp	Method: Laser Automation: CM WD: 200 mm FR: 300 mm/s Models (2)	Method: Saw Automation: CD, CM WD: 300 mm FR: 1,000 mm/s Models (6)	